MBRAF3200, NRVBAF3200

Surface Mount Schottky Power Rectifier

This device employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very High Blocking Voltage 200 V
- 150°C Operating Junction Temperature
- Guard-Ring for Stress Protection
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- This is a Pb–Free Device

Mechanical Charactersistics

- Case: Epoxy, Molded, Epoxy Meets UL 94, V-0
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Cathode Polarity Band
- Device Meets MSL 1 Requirements
- ESD Ratings: Machine Model = A Human Body Model = 1B

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current $(T_L = 100^{\circ}C)$	I _{F(AV)}	3.0	A
Non–Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	100	A
Operating Junction Temperature	Τ _J	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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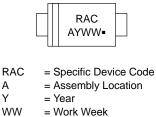
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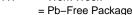
SCHOTTKY BARRIER RECTIFIER 3.0 AMPERE 200 VOLTS



SMA-FL CASE 403AA STYLE 6

MARKING DIAGRAM





ORDERING INFORMATION

Device	Package	Shipping [†]
MBRAF3200T3G	SMA-FL (Pb-Free)	5000 / Tape & Reel
NRVBAF3200T3G	SMA-FL (Pb-Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MBRAF3200, NRVBAF3200

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1 Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{ heta JL} \ R_{ heta JA}$	25 90	°C/W

1. 1 inch square pad size $(1 \times 0.5 \text{ inch})$ for each lead on FR4 board.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 2) (I _F = 3.0 A, T _J = 25°C) (I _F = 4.0 A, T _J = 25°C) (I _F = 3.0 A, T _J = 150°C)	V _F	0.84 0.86 0.62	V
Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_J = 25^{\circ}C$) (Rated dc Voltage, $T_J = 150^{\circ}C$)	I _R	1.0 6.0	mA mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

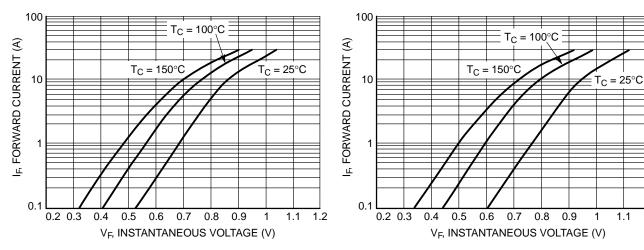




Figure 2. Maximum Forward Voltage

1.2

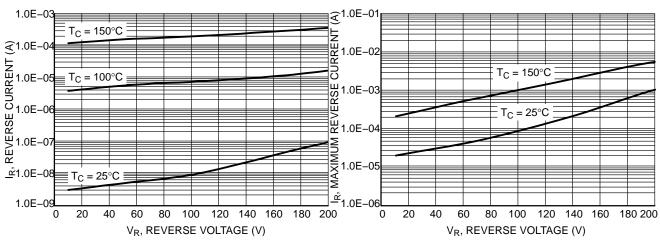


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

MBRAF3200, NRVBAF3200

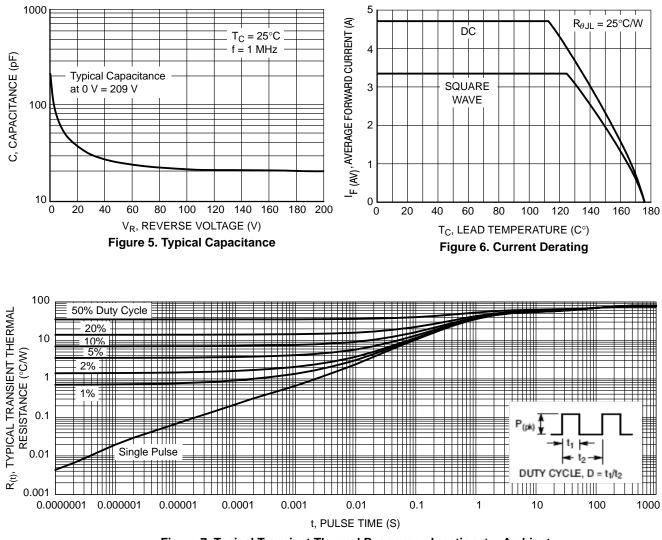
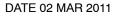


Figure 7. Typical Transient Thermal Response, Junction-to-Ambient



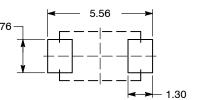


SMA-FL CASE 403AA-01 ISSUE O



Е E1 1 D TOP VIEW **↓**A С SIDE VIEW 2X b - 2X L **BOTTOM VIEW** RECOMMENDED **SOLDER FOOTPRINT*** 5.56 1.76

NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. MILLIMETERS DIM MIN MAX A 0.90 1.10 b 1.25 1.65 c 0.15 0.30 D 2.40 2.80 E 4.80 5.40 E 4.80 5.40 E 4.00 4.60 L 0.70 1.10



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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